

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	RELEASE BY SECURED PARTY
CONVEYING PARTY DATA	
Name	Execution Date
Bank of America, N.A.	11/10/2009
RECEIVING PARTY DATA	
Name:	Research Foundation of the City University of New York
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Internal Address:	11th Floor
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State/Country:	NEW YORK
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Patent Number:	7119359
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ATTORNEY DOCKET NUMBER:	46124.090387
NAME OF SUBMITTER:	Edward T. White
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PATENT
REEL: 023594 FRAME: 0129


RELEASE OF CERTAIN PATENTS

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, BANK OF AMERICA, N.A., as administrative agent (the "Agent") does hereby terminate and release its interests and rights in the patents and patent applications listed on Schedule 1 hereto arising under the certain Patent Security Agreement dated April 16, 2009 between AMKOR TECHNOLOGY, INC. and the Agent, which was recorded in the United States Patent and Trademark Office on June 3, 2009, at Reel/Frame Numbers 022764/0864 (the "Patent Security Agreement"). The Agent retains all of its interests and rights in all of the Patent Collateral (as such term is defined in the Patent Security Agreement) that is not listed on Schedule 1 hereto.

Dated: November 10, 2009

Agent

BANK OF AMERICA, N.A.

By: 
Name: Jay L. Bartholomew
Title: Senior Vice President

SCHEDULE 1

#	USPN	Issued	Title
467	7,119,359	04/03/07	Camera Module Fabrication Method Including Singulating A Substrate
9	11/111,316	04/21/05	Trace Fill Substrate For Die Attach Film and Semiconductor Package Using The Same
54	11/765,858	06/20/07	Embedded Die Metal Etch Stop Fabrication Method And Structure
93	12/183,779	07/31/08	Stacked Inverted Flip Chip Package And Fabrication Method
128	12/339,772	03/03/09	Semiconductor Device

RELEASE OF CERTAIN PATENTS, Schedule 1
46124.090387 EMF_US 28670373v1

RECORDED: 12/02/2009

PATENT
REEL: 023594 FRAME: 0131